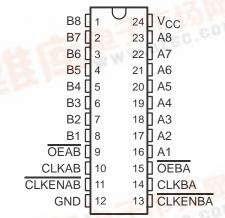
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus-Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), and Ceramic (JT) DIPs

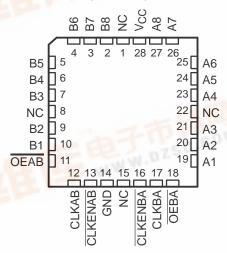
description

These octal bus transceivers and registers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

SN54LVTH2952...JT PACKAGE SN74LVTH2952...DB, DGV, DW, OR PW PACKAGE (TOP VIEW)



SN54LVTH2952 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The 'LVTH2952 devices consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input, provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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description (continued)

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

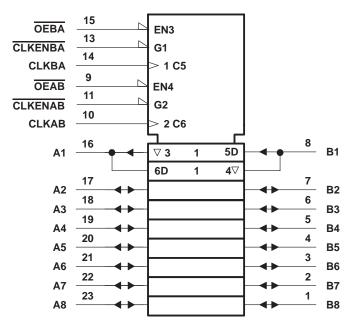
The SN54LVTH2952 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH2952 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

	OUTPUT			
CLKENAB	CLKAB	OEAB	В	
Н	Χ	L	Χ	в ₀ ‡
Х	H or L	L	Χ	В ₀ ‡ В ₀ ‡
L	\uparrow	L	L	L
L	\uparrow	L	Н	Н
Х	X	Н	Χ	Z

[†] A-to-B data flow is shown; B-to-A data flow is similar but uses CLKENBA, CLKBA, and OEBA.

logic symbol§



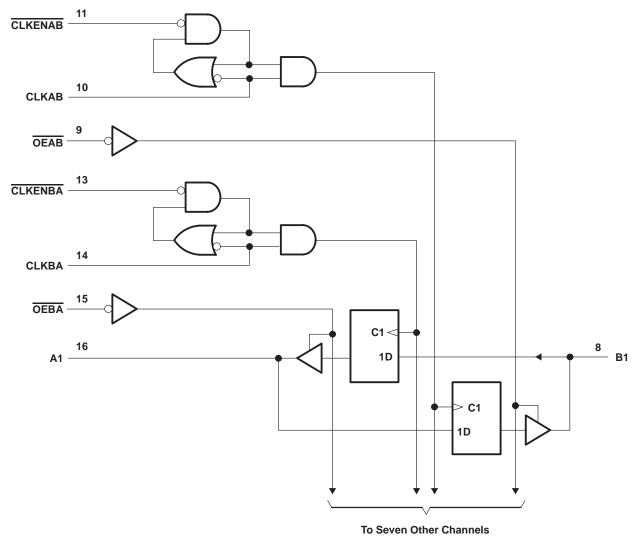
[§] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DGV, DW, JT, and PW packages.



[‡]Level of B before the indicated steady-state input conditions were established

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logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, JT, and PW packages.

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[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Storage temperature range, T_{stg} –65°C to 150°C

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

		SN54LVT	H2952	SN74LVT	UNIT		
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	7	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage	4	5.5		5.5	V	
IOH	High-level output current		1	-24		-32	mA
l _{OL}	Low-level output current		2	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	⁷ 0 ₂	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	·	200		200		μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			4LVTH2	952	SN7	4LVTH2	952	UNIT		
FAI	KAWETEK	1231 C	DINDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT		
V_{IK}		$V_{CC} = 2.7 \text{ V},$	$I_{\parallel} = -18 \text{ mA}$			-1.2			-1.2	V		
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	VCC-0	.2		VCC-0	.2				
\/		$V_{CC} = 2.7 \text{ V},$	I _{OH} = -8 mA 2.4			2.4			V			
VOH		V 2.V	I _{OH} = -24 mA	2						V		
		VCC = 3 V	I _{OH} = -32 mA				2					
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2			
		VCC = 2.7 V	I _{OL} = 24 mA			0.5			0.5			
Vo			I _{OL} = 16 mA			0.4			0.4	V		
VOL		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	I _{OL} = 32 mA			0.5	0.5			V		
		VCC = 3 V	I _{OL} = 48 mA			0.55						
			I _{OL} = 64 mA				0.55					
	Control innuts	V _{CC} = 3.6 V,	V _I = V _{CC} or GND			\$ ±1			±1			
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		Š	10	10					
II	A or B ports‡	V _{CC} = 3.6 V	V _I = 5.5 V	20			20			μΑ		
			$V_I = V_{CC}$									
			V _I = 0		5	-5			- 5			
l _{off}		$V_{CC} = 0$,	V_{I} or $V_{O} = 0$ to 4.5 V	0)				±100	μΑ		
		Vac - 2 V	V _I = 0.8 V	75			75					
I _I (hold)	A or B ports	VCC = 3 V	V _I = 2 V	-75	– 75			- 75				
		V _{CC} = 3.6 V§,	V _I = 0 to 3.6 V						±500			
I _{OZPU}		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	0.5 V to 3 V,			±100*			±100	μΑ		
I _{OZPD}	IOZPD $\frac{V_{CC} = 1.5 \text{ V to 0, V}_{O} = 0}{OE = \text{don't care}}$		0.5 V to 3 V,			±100*			±100	μΑ		
Icc		V _{CC} = 3.6 V,	Outputs high			0.19			0.19			
		$I_{O} = 0$,	Outputs low	5		5 0.19			mA			
		$V_I = V_{CC}$ or GND	Outputs disabled	0.19								
ΔI_{CC} $V_{CC} = 3 \text{ V to } 3.6 \text{ V, On}$ Other inputs at V_{CC} or					0.2			0.2	mA			
Ci		V _I = 3 V or 0			4			4		pF		
C _{io}		V _O = 3 V or 0			9			9		pF		

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] Unused terminals at V_{CC} or GND

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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timing requirement over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			;	SN54LVTH2952				SN74LVTH2952				
			$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CC} = 2.7 \text{ V}$		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT			
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock} Clock frequency				150		150		150		150	MHz	
t _W Pulse duration			CLK high	3.3		3.3		3.3		3.3		
		CLK low	3.3		3.3		3.3		3.3		ns	
		· <u> </u>	Data high	1.6		2.2		1.5		2.1		
۱.	t _{Su} Setup time		Data low	1.6	6	2.2		1.5		2.1		ns
^l su			Data high	1.6	30	1.9		1.5		1.8		115
	CE before CLK↑	Data low	2	00	2.6		1.9		2.5			
t _h Hold time	A or B after CLK↑ CE after CLK↑		1	Q	0.2		1		0.2			
			1.2		0.2		1.2		0.2		ns	

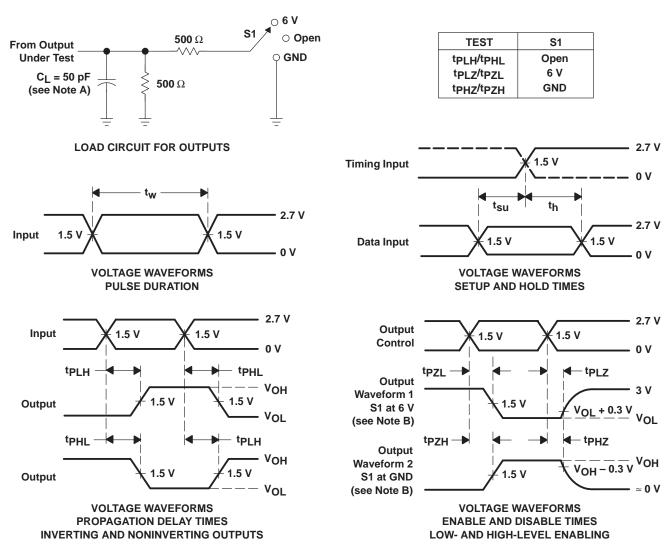
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVTH2952				SN74LVTH2952						
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
f _{max}			150		150		150			150		MHz	
^t PLH	CLKBA or CLKAB	CLKBA or	A or B	1.2	4.8	N.	5.5	1.3	2.9	4.6		5.3	ns
^t PHL		AOIB	1.2	4.8	TA.	5.5	1.3	3.1	4.6		5.3	115	
^t PZH	OEBA or OEAB	A or B	1	4.8	,	5.9	1.1	2.6	4.6		5.8	ns	
tPZL	OEBA OF OEAB	AUID	1	4.8		5.9	1.1	3	4.6		5.8	115	
^t PHZ	OEBA or OEAB	OEBA or OEAB	A or B	1.2	5.6		6	1.3	3.6	5.4		5.9	nc
t _{PLZ}	OLDA OF OLAB	AUID	1.5	5.4		5.6	1.6	3.6	5.1		5.3	ns	

[†] All typical values are at $T_A = 25$ °C.

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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